

MILITARY SPECIFICATION

SEMICONDUCTOR DEVICE, TRANSISTOR, NPN, SILICON SWITCHING
TYPES 2N2481 AND TX2N2481

This amendment forms a part of Military Specification MIL-S-19500/268C, dated 25 June 1971, and is approved for use by all Departments and Agencies of the Department of Defense.

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3.3.1, delete and substitute:

"3.3.1 Lead material and finish. Lead material shall be Kovar or Alloy 52. Lead finish shall be gold- or tin-plated. Where a choice of lead material and finish is desired, it shall be specified in the contract or order (see 6.2)."

3.3.3.1: Delete in its entirety.

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TABLE II, subgroups 2 and 4, hermetic seal, "Details" column, delete and substitute:
"Test cond. G or H or fine leaks; test cond. A, B, C, D, or F for gross leaks"

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4.5.5.2, delete and substitute:

"4.5.5.2 Gross-leak test. All devices shall be tested for gross-leaks in accordance with MIL-STD-750, method 1071, test condition A, B, C, 0, or F."

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6.2, delete and substitute:

"6.2 Ordering data. Procurement documents should specify the following:

- (a) Lead material and finish if preference exists (see 3.3.1).
- (b) Inspection data (see 4.3)."

Custodians:

Army - EL
Navy - EC
Air Force - 17

Preparing activity:
Navy - EC

Review activities:

Army - MI, MU
Air Force — 11, 19, 80, 85
NASA - NA
DSA-ES

Agent:
DSA - ES

(Project 5961-0572)

User activities:

Army - AV, SM
Navy - AS, CG, MC, SH, OS
Air Force - 13, 15